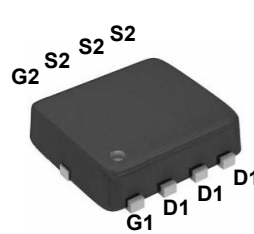
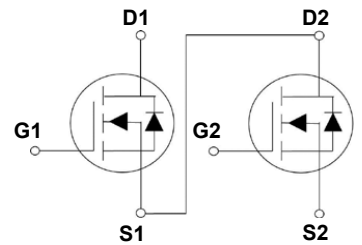
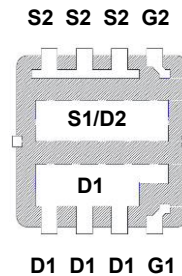


Main Product Characteristics

V_{DSS}	30V
$R_{DSON(max.)}$	10.5mΩ
I_D	19.5A



PPAK3X3



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The SSFN3810H utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current – Continuous ($T_C=25^\circ\text{C}$)	I_D	19.5	A
Drain Current – Continuous ($T_C=100^\circ\text{C}$)		12.3	A
Drain Current – Continuous ($T_A=25^\circ\text{C}$)		10.8	A
Drain Current – Continuous ($T_A=100^\circ\text{C}$)		6.8	A
Drain Current – Pulsed ¹	I_{DM}	78	A
Single Pulse Avalanche Energy ²	E_{AS}	13	mJ
Single Pulse Avalanche Current ²	I_{AS}	16	A
Power Dissipation ($T_C=25^\circ\text{C}$)	P_D	27	W
Power Dissipation – Derate above 25°C		0.01	W/ $^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 to +150	$^\circ\text{C}$
Operating Junction Temperature Range	T_J	-55 to +150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	---	62	$^\circ\text{C/W}$
Thermal Resistance Junction to Case	$R_{\theta JC}$	---	4.6	$^\circ\text{C/W}$

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static State Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	30	---	---	V
BV_{DSS} Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to 25°C , $I_D=1\text{mA}$	---	0.04	---	$V/^\circ\text{C}$
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=30V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{DS}=24V, V_{GS}=0V, T_J=125^\circ\text{C}$	---	---	10	μA
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
Static Drain-Source On-Resistance ³	$R_{DS(on)}$	$V_{GS}=10V, I_D=10A$	---	8.5	10.5	$m\Omega$
		$V_{GS}=4.5V, I_D=5A$	---	11	14	$m\Omega$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.6	2.5	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$		---	-4	---	$mV/^\circ\text{C}$
Forward Transconductance	g_{fs}	$V_{DS}=5V, I_D=5A$	---	12	---	S
Dynamic Characteristics						
Total Gate Charge ^{3, 4}	Q_g	$V_{DS}=15V, V_{GS}=10V, I_D=5A$	---	15.6	31	nC
Gate-Source Charge ^{3, 4}			---	2.3	5	
Gate-Drain Charge ^{3, 4}	Q_{gd}		---	3	6	
Turn-On Delay Time ^{3, 4}	$T_{d(on)}$	$V_{DD}=15V, V_{GS}=10V, R_G=6\Omega, I_D=1A$	---	3.8	7	nS
Rise Time ^{3, 4}	T_r		---	10	19	
Turn-Off Delay Time ^{3, 4}	$T_{d(off)}$		---	22	42	
Fall Time ^{3, 4}	T_f		---	6.6	13	
Input Capacitance	C_{iss}	$V_{DS}=25V, V_{GS}=0V, F=1\text{MHz}$	---	620	900	pF
Output Capacitance	C_{oss}		---	85	125	
Reverse Transfer Capacitance	C_{rss}		---	60	90	
Gate Resistance	R_g	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	---	2.8	5.6	Ω
Drain-Source Diode Characteristics						
Continuous Source Current	I_S	$V_{GS}=V_D=0V, \text{Force Current}$	---	---	19.5	A
Pulsed Source Current ³	I_{SM}		---	---	39	A
Diode Forward Voltage ³	V_{SD}	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1	V

Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}$, Q1: $I_{AS}=16A$, Q2: $I_{AS}=42A, R_G=25\Omega$, Starting $T_J=25^\circ\text{C}$.
3. The data tested by pulsed, pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.

Typical Electrical and Thermal Characteristic Curves

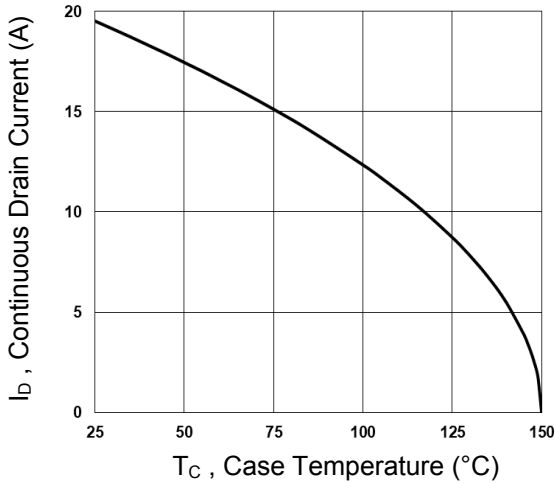


Fig.1 Continuous Drain Current vs. T_c

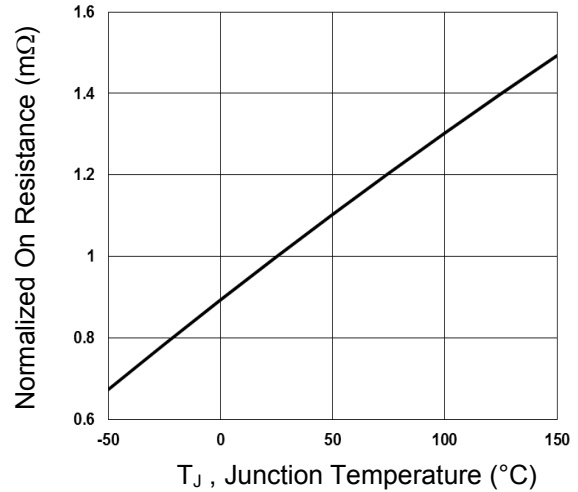


Fig.2 Normalized R_{DS(on)} vs. T_J

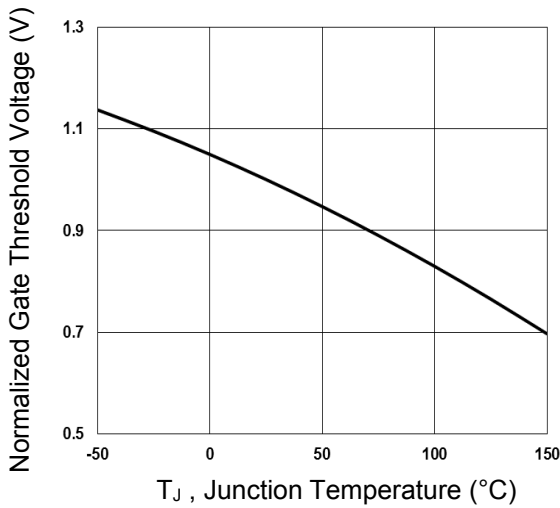


Fig.3 Normalized V_{th} vs. T_J

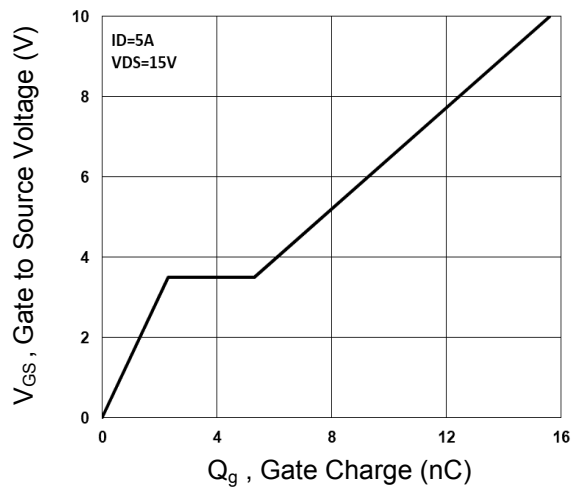


Fig.4 Gate Charge Waveform

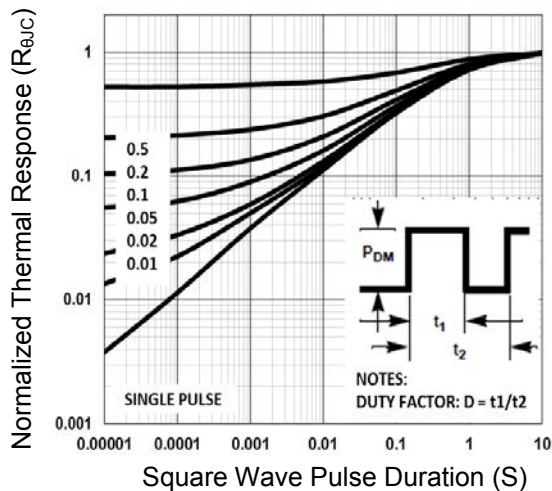


Fig.5 Normalized Transient Impedance

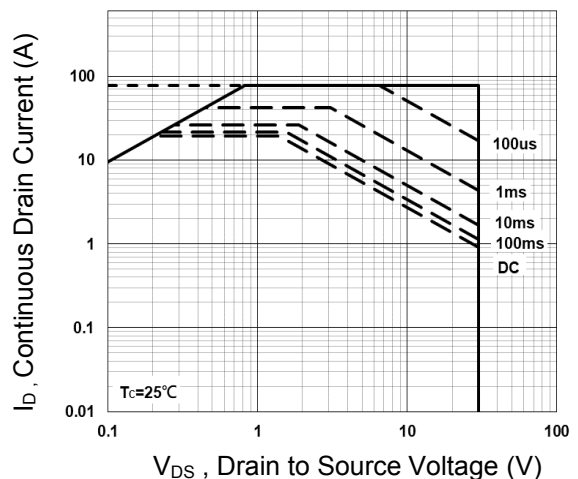


Fig.6 Maximum Safe Operation Area

Typical Electrical and Thermal Characteristic Curves

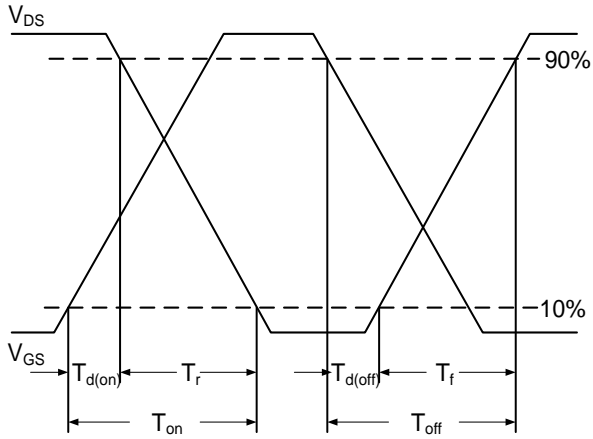


Fig.7 Switching Time Waveform

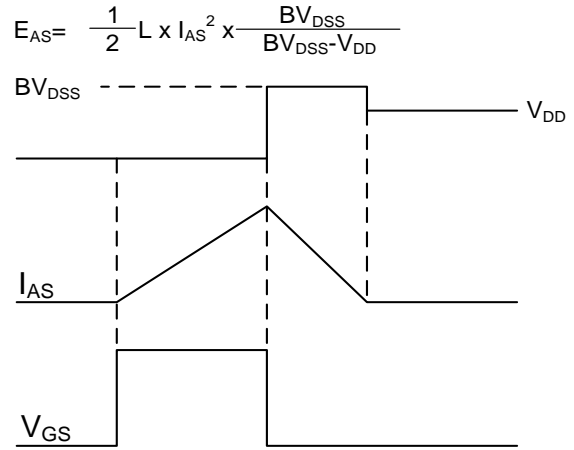
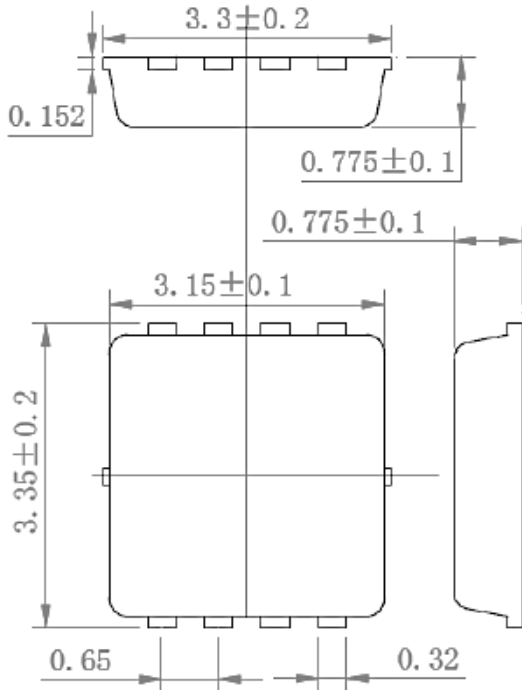
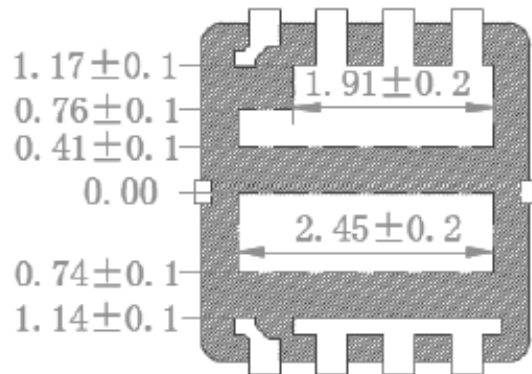


Fig.8 E_{AS} Waveform

Package Outline Dimensions



PPAK3X3 Asymmetric Dual Pin



Suggested Pad Layout

